

Title (en)  
METHOD OF MANUFACTURING ELECTRONIC DEVICE

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN VORRICHTUNG

Title (fr)  
PROCÉDÉ DE FABRICATION D'UN DISPOSITIF ÉLECTRONIQUE

Publication  
**EP 3840027 B1 20230524 (EN)**

Application  
**EP 20212761 A 20201209**

Priority  
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Abstract (en)  
[origin: EP3840027A1] A method of manufacturing an electronic device, comprising: providing a carrier substrate with a plurality of light-emitting units disposed thereon, the plurality of light-emitting units being spaced with a first pitch (P1) in a first direction and a second pitch (P2) in a second direction that is perpendicular to the first direction; providing a driving substrate; and transferring at least a portion of the plurality of light-emitting units to the driving substrate to form a transferred portion of the plurality of light-emitting units on the driving substrate, the transferred portion being spaced with a third pitch (P3) in a third direction and a fourth pitch (P4) in a fourth direction that is perpendicular to the third direction; wherein the first pitch (P1), the second pitch (P2), the third pitch (P3), and the fourth pitch (P4) are satisfied following relations:  $P3=mP1$ ; and  $P4=nP2$ , m and n are positive integers.

IPC 8 full level  
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